

SOT2165-1

TFBGA306, thin fine-pitch ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 1.258 mm body

3 March 2022

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA306
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	11-05-2021
Manufacturer package code	98ASA01873D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	11	-	mm
package width	-	11	-	mm
seated height	-	1.258	1.36	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	306	-	



TFBGA306, thin fine-pitch ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 1.258 mm body

2 Package outline

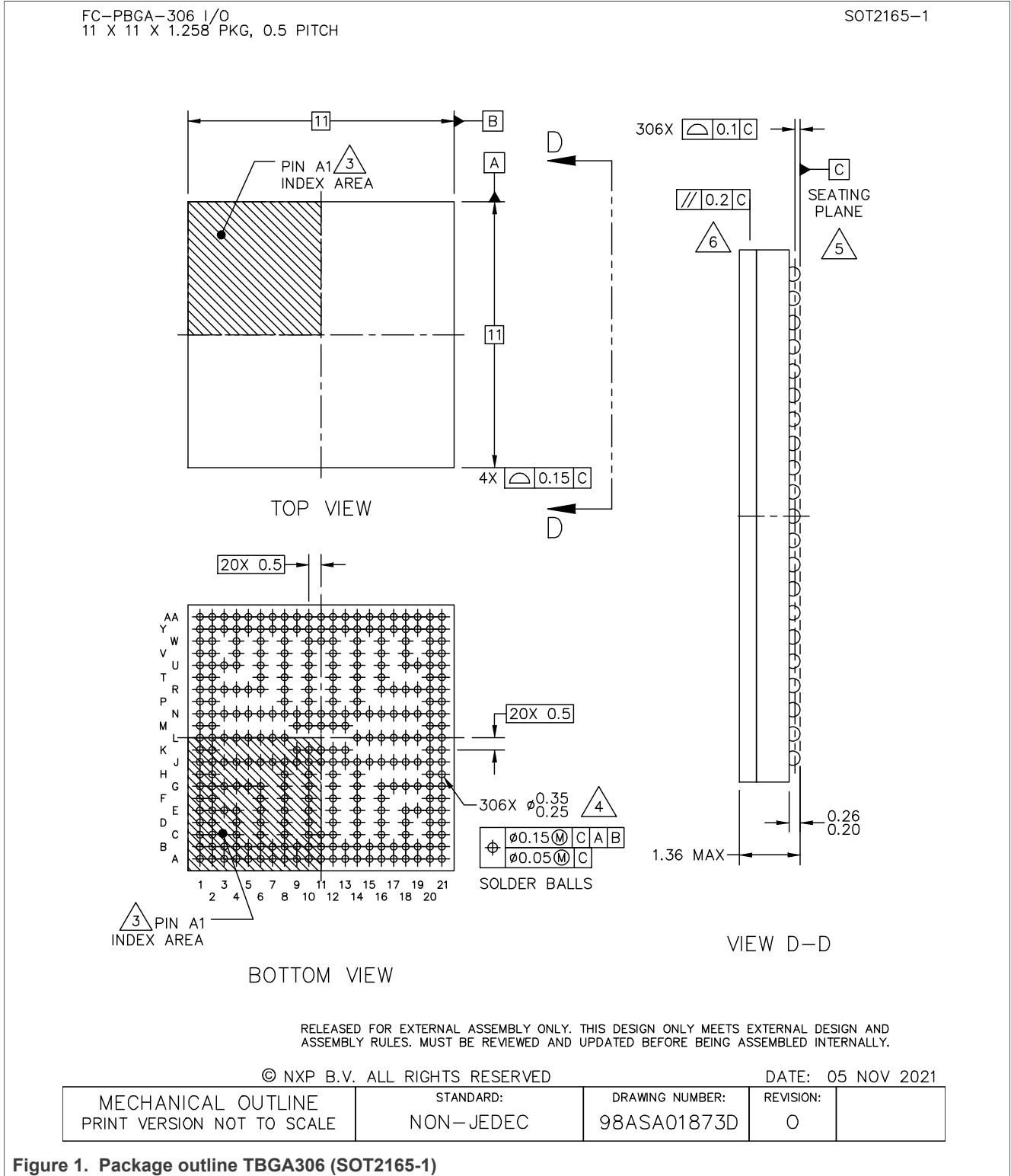
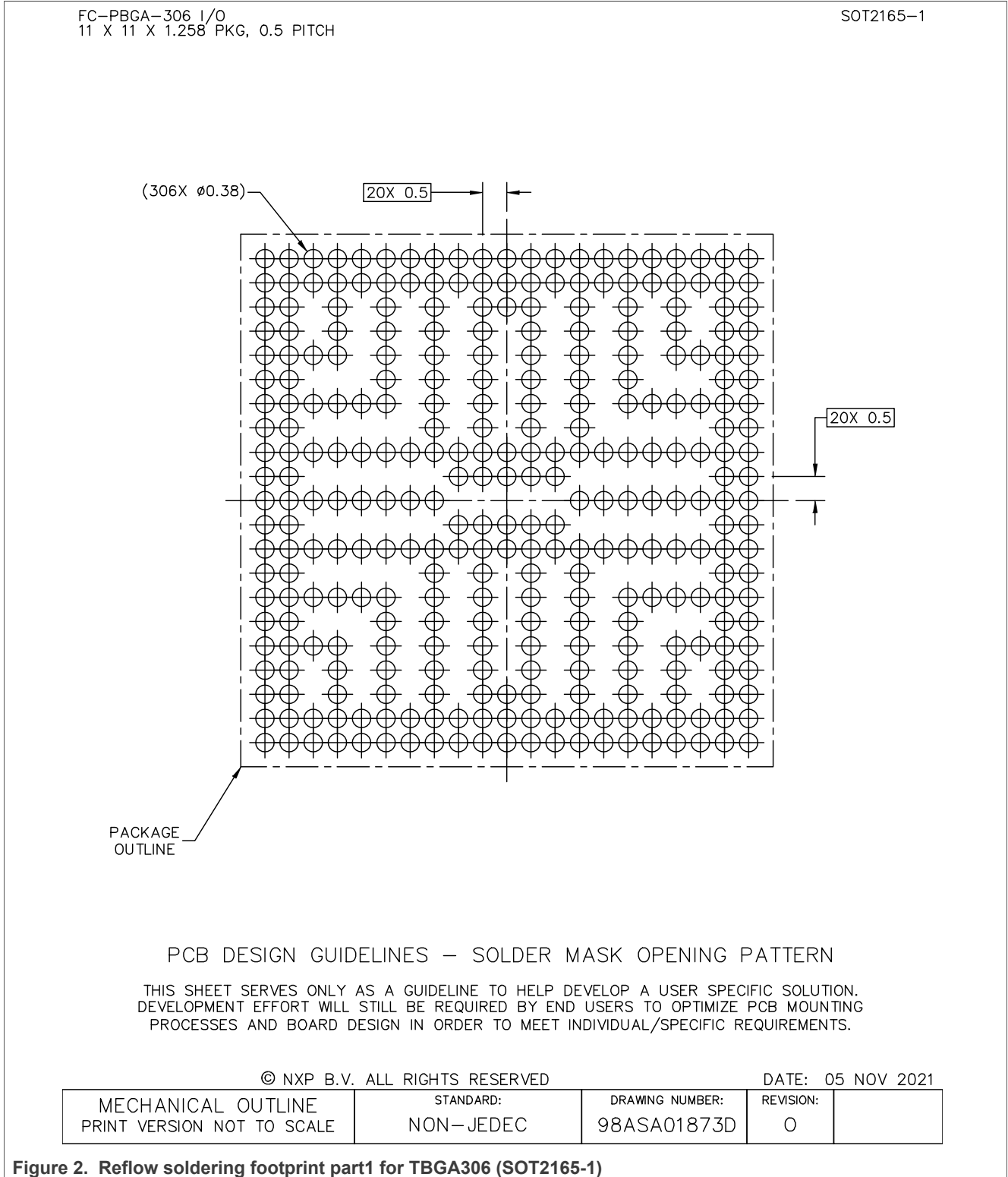


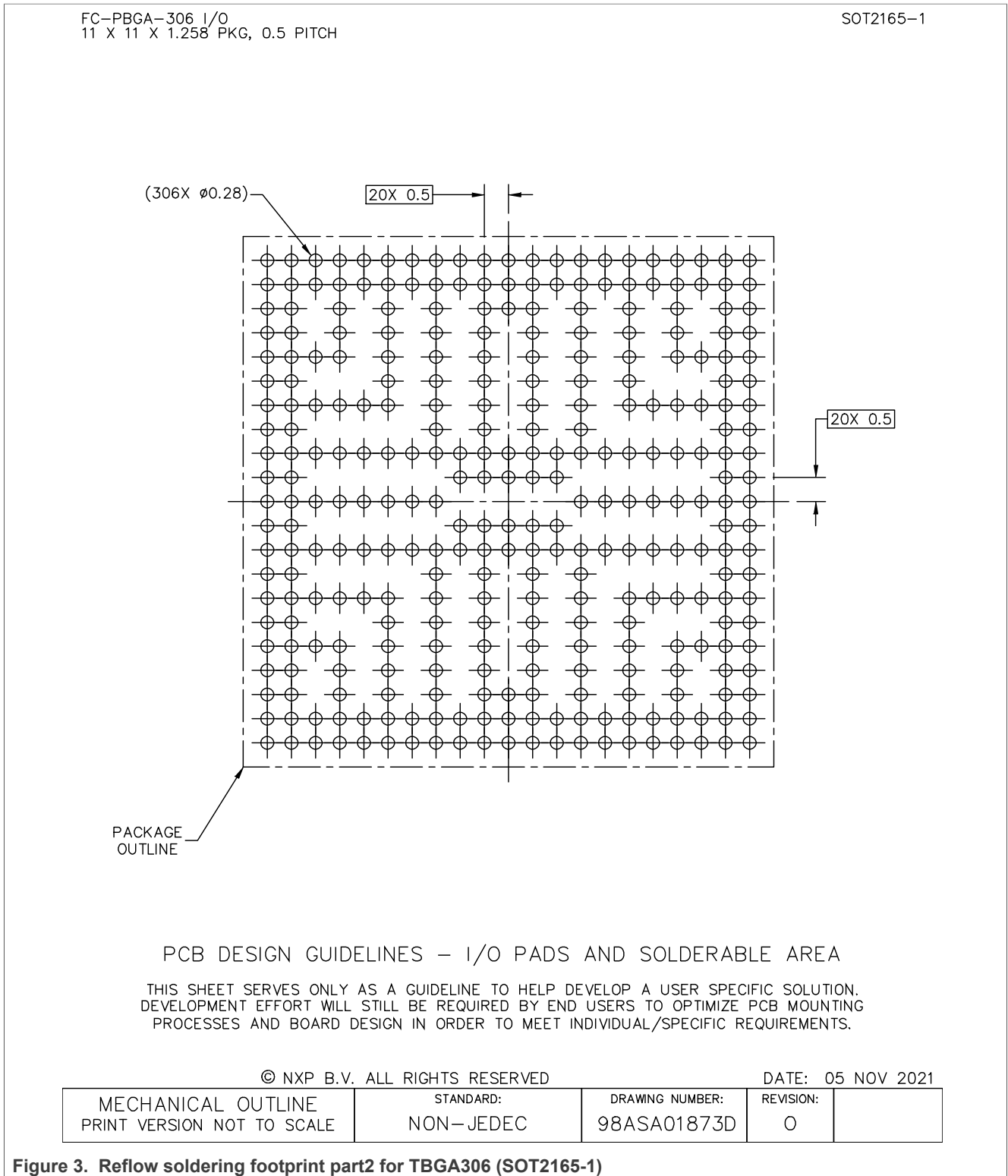
Figure 1. Package outline TPGA306 (SOT2165-1)

TFBGA306, thin fine-pitch ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 1.258 mm body

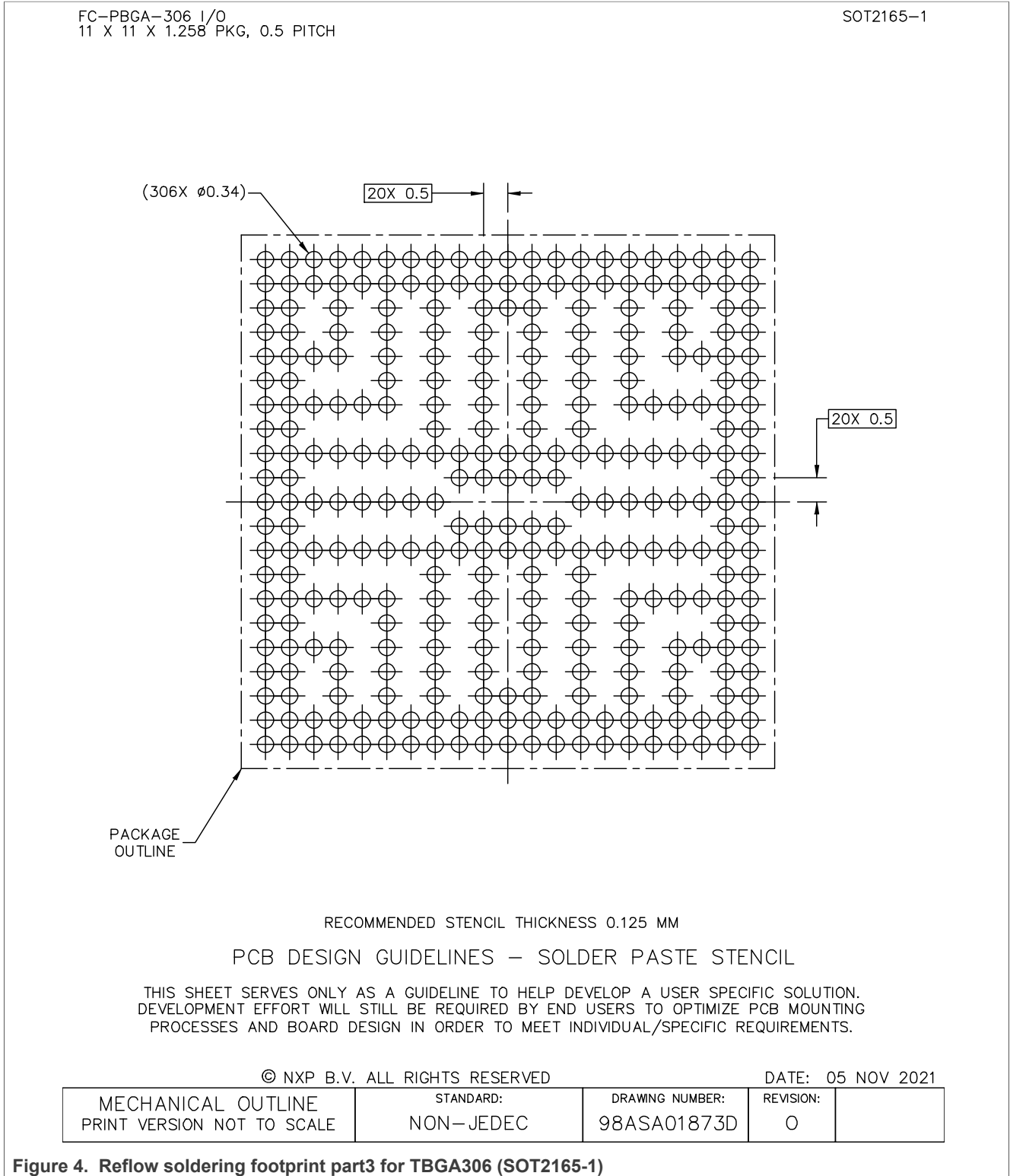
3 Soldering



TFBGA306, thin fine-pitch ball grid array package, 306 terminals, 0.5 mm pitch, 11 mm x 11 mm x 1.258 mm body



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FC-PBGA-306 I/O
11 X 11 X 1.258 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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DATE: 05 NOV 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01873D	REVISION: 0	
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Figure 5. Package outline note TBGA306 (SOT2165-1)

4 Legal information

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